In the Claims

The current status of all claims is shown by the following listing (in accordance with the Revised Notice "Amendments May Now Be Submitted in Revised Format" of 02/13/03):

Claims 1-10 (Cancelled)

Claims 11-20 (cancelled)

--21. (New) The method of reducing electromagnetic interference generated within an integrated circuit device package wherein the integrated circuit device package comprises

a wafer having wafer circuitry disposed thereon;

a plurality of conductors defining electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry; and

a structure that encapsulates and supports the wafer;

said method comprising applying magnetic material that exhibits a lossy characteristic, in the vicinity of at least one of the electrically conductive paths such that the magnetic material is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, to attenuate the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing associated with the series inductance of the at least one of the electrically conductive paths.--

--22. (New) The method of claim 21, wherein the structure that encapsulates and supports the wafer comprises an encapsulating medium, and said method further comprises introducing magnetic material that exhibits a lossy characteristic into the encapsulating

medium such that the magnetic material is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, so as to cause the series inductance of the at least one of the electrically conductive paths to behave as a lossy inductor so as to attenuate the highest frequency signal components while introducing generally little inductance effects of overshoot and ringing.--

B2

--23. (New) The method of claim 22, wherein a relatively small amount of magnetic material that exhibits a lossy characteristic, is introduced into the encapsulating medium such that the magnetic material is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, and so that the relative permeability in the vicinity of the at least one of the electrically conductive paths is not so high as to cause significant mutual coupling with other of the plurality of conductors.--

--24. (New) The method of claim 23, where the introduction of the relatively small amount of magnetic material that exhibits a lossy characteristic, such that the magnetic material is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, results in a relative permeability of the encapsulating medium that is sufficient to desirably affect the series inductance of the at least one of the electrically conductive paths..--

--25. (New) The method of claim 23, where the mutual inductance between the one of the plurality of electrically conductive

paths and an adjacent conductor is small with respect to the self-inductance of each conductor.--

--26. (New) The method of claim 21, wherein the magnetic material that is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, is applied such that mutual coupling of the one of the plurality of electrically conductive paths and an adjacent conductor is substantially eliminated.--

B2

--27. (New) The method of claim 21, where the magnetic material that exhibits a lossy characteristic and is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, substantially surrounds the one of the plurality of the electrically conductive paths and effectively chokes undesired high frequency signals immediately external to the at least one of the electrically conductive paths without substantially affecting data signals passing therethrough.--

--28. (New) The method of claim 27, where the structure that encapsulates and supports the wafer comprises an encapsulating medium that is substantially free of magnetic material.--

--29. (New) The method of claim 27, where the structure that encapsulates and supports the wafer comprises an encapsulating medium that contains a small amount of magnetic material that is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, to further achieve the reduction of electromagnetic interference.--

--30. (new) The method of claim 27, where the magnetic material that is not part of any of the electrically conductive paths for carrying all of the electric current flowing to and from the wafer circuitry, substantially surrounds the one of the plurality of electrically conductive paths, at the portion of such one electrically conductive path relatively near to the wafer.--